

## WHAT IS CLAIMED IS:

1. A small outline leadless package comprising:
  - (a) a molding compound encapsulating discrete semiconductor devices comprising one of a solder contact bump  
5 small outline integrated circuit and a solder contact bump small outline transistor to form a package having a top, bottom, and four side surfaces;
  - (b) a pair of electrical contacts each contacting a solder contact bump and extending to and flush with one of said surfaces;
  - 10 (c) each of said electrical contacts providing an exposed contact surface co-planar with said one of said surfaces and terminating at a junction between said one of said surfaces and another of said surfaces; and
  - (d) the termination of said contacts occurring only at  
15 oppositely disposed package surfaces.
2. The combination set forth in Claim 1 wherein said one of  
said surfaces is a top or bottom surface and said another of said surfaces is a  
side surface.  
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3. The combination set forth in Claim 1 wherein each of said  
electrical contacts include longitudinally extending notches.
4. The combination set forth in Claim 1 wherein the exposed  
25 contact surface of said electrical contacts is shaped to identify the electrical function of the encapsulated device.
5. The combination set forth in Claim 1 wherein one of said  
electrical contacts is S-shaped for contacting solder bumps on a surface of  
30 said discrete semiconductor device and wherein a second electrical contact is planar and contacts solder contact bumps on an opposite side of said discrete semiconductor device.

6. A small outline leadless package comprising:

(a) a molding compound encapsulating discrete semiconductor devices comprising one of a solder contact bump small outline integrated circuit solder contact bump small outline transistor to form a package having top, bottom and four side surfaces;

(b) a pair of S-shaped electrical contacts each contacting a solder contact bump and extending to and flush with one of said surfaces, said electrical contacts contacting solder bumps on a top surface of the encapsulated device and extending to a bottom surface of said package;

(c) each of said electrical contacts providing an exposed contact surface coplanar with one of said package surfaces and terminating at a junction between said one of said package surfaces and another of said package surfaces; and

(d) the termination of said contacts occurring only at oppositely disposed package surfaces.

7. The small outline leadless package of Claim 6 wherein said one of said surfaces is a bottom package surface and another of said surfaces is a side package surface.

8. A small outline leadless package comprising:

(a) a molding compound encapsulated discrete semiconductor device comprising one of a solder contact bump small outline integrated circuit and a solder contact bump small outline transistor to form a package having a top, bottom and four side surfaces;

(b) a pair of L-shaped electrical contacts each contacting a solder contact bump and extending to and flush with two of said package surfaces;

(c) said electrical contacts providing an exposed contact

surface coplanar with each of said two package surfaces and terminating at a junction between said two package surfaces; and

(d) the termination of said contacts occurring only at oppositely disposed package surfaces.

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9. The small outline leadless package of Claim 8 wherein said discrete semiconductor device is mounted between two vertically extending legs of opposing L-shaped electrical conductors.